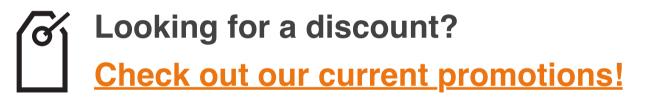


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   Graphics Specifications
       Expansion Options
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- Essentials		Products formerly Skylake	
Status	Launched		
Launch Date	Q4'15	CONFLICT	
Bus Speed	8 GT/s DMI3	CF CONFLICT	
Embedded Options Available	Yes		
Lithography	22 nm	Learn how Intel is pursuing conflict-free technology. >	
TDP	6 W		
Recommended Customer Price	\$49.00		
Conflict Free	Yes		
Datasheet	Link		
Supports Overclocking	No	Visit the Embedded Design Center >	
- Memory Specifications		Quick Links	
# of DIMMs per channel	2		
		Export Full Specifications >	
- Graphics Specifications		Support Overview > Search Distributors >	
# of Displays Supported [‡]	3		
- Expansion Options		PCN/MDDS Information	
PCI Support	No	SR2CC 943517: PCN MDDS	
PCI Express Revision	3.0		
PCI Express Configurations [‡]	x1, x2, x4		
Max # of PCI Express Lanes	20		
- I/O Specifications			
USB Revision	3.0/2.0		
# of USB Ports	14		
USB 3.0	Up to 10		
Max # of SATA 6.0 Gb/s Ports	8		
RAID Configuration	0/1/5/10		
Integrated LAN	Integrated MAC		
Supported Processor PCI Express Port Revision	3		
Supported Processor PCI Express Port Configurations	1x16, 2x8, 1x8+2x4		
- Package Specifications			
Package Size	23mm x 23mm		
Low Halogen Options Available	See MDDS		
- Advanced Technologies			
Intel® Virtualization Technology for Directed I/O (VT-d) [‡]	Yes		
Intol® vPro Tochnology ‡	Vec		

Yes

Intel[®] vPro Technology [‡]

Intel® ME Firmware Version	11.0			
Intel® Rapid Storage Technology	Yes			
Intel® Rapid Storage Technology enterprise	Yes			
Intel® Node Manager	Yes			
Intel® Standard Manageability	Yes			
Intel® Smart Response Technology	Yes			
- Intel® Platform Protection Technology				
Trusted Execution Technology [‡]	Yes			

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

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WARNING: Altering clock frequency and/or voltage may: (i) reduce system stability and useful life of the system and processor; (ii) cause the processor and other system components to fail; (iii) cause reductions in system performance; (iv) cause additional heat or other damage; and (v) affect system data integrity. Intel has not tested, and does not warranty, the operation of the processor beyond its specifications. Intel assumes no responsibility that the processor; including if used with altered clock frequencies and/or voltages, will be fit for any particular purpose. For more information, visit http://www.intel.com/content/www/us/en/gaming/overclocking-intel-processors.html



